

Name : KUMARADEVAN, SANTANA DEWAN

Address: 10, LENGKOK BAYAN, TAMAN NIBONG TEBAL,
NIBONG TEBAL, 14300, Penang, Malaysia

Email : devansantana5352@gmail.com

Tel : 60-04-5936887(Home),
0168819438(Mobile),
0125708090(Mobile)

Highest Education : Bachelor's Degree in Engineering (Electrical/Electronic)
(University of Lincoln, UK)

Years of Experiences : 16

Expected Salary : MYR 5900

Employment History :

Current Position : QUALITY ASSURANCE MANAGER

Company : Formach Asia Sdn.Bhd

Duration : (Sept 2013 - "as of present")

Industry : Sheet metal fabrication.

Current Specialization: Quality Control/Assurance

Work Description :

- 1) Ensure Company's Quality System and applicable regulator requirements such as ISO 9001 and ISO 14001.
- 2) Oversee "Quality Assurance" activities of precision sheet metal, forming and fabrication work.
- 3) Leads a team of 8 personals for IQC, IPQC and OQC and SQE in the facility and responsible for the overall Quality Environmental System function team.
- 4) Ensure that all inspection and testing are carried out according to the requirements of the products as in the customer drawing.
- 5) Responsible as QMR (Quality Management Representative) to review key indicators of "Quality Objective" and technical problems/procedures of departments and recommend solutions to problems or changes in SOP procedures.
- 6) Responsible as customer representative to handle customer complaints. Ensure corrective actions are carried out within quality specifications and requirements.
- 7) Initiate action to prevent the occurrence of nonconformities relating to the product, process and quality system.
- 8) Evaluates and analyses on in-house quality problems or on customer return parts together with process engineer.
- 9) Conduct Weekly Quality Meeting to discuss internal and customer quality issues and come out preventive measurement.

Project achievement:

- 1)Lead a team of engineers to drive critical quality KPI such as 8D cycle time and 8D quality.8d respond time improved 40% and 8D cycle time at 10%.
- 2)Driving for Quality Improvement activity with engaging engineering and operational team and achieved improvement factor of 20% at IPQC and 0.5% at OQC.
- 3)Implemented daily OQC Wip Management system for better productivity of OQC.

Singatronics(M) Sdn.Bhd (May 2011 -August 2013)

Position Title (Level) : QUALITY ASSURANCE MANAGER (Manager)

Specialization : Quality Control/Assurance

Role : Quality Control/Assurance

Industry : PCBA Manufacturing / Production

Monthly Salary : MYR 5700

Work Description :

- 1)Leads a team of 15 personals for IQC, IPQC and OQC and SQE in the facility and responsible for the overall Quality Management System function team.
- 2)Responsible as QMR (Quality Management Representative) to review key indicators of "Quality Objective" and technical problems/procedures of departments and recommend solutions to problems or changes in SOP procedures.
- 3)Responsible to manage the overall KPI of all dept to meet baseline line level and improve on the indicator value.
- 4)Responsible as customer representative to handle customer's complaints and ensure complaints are well addressed.
- 5)Ensure compliance with the Company's Quality System and applicable regulatory requirements such as ISO 9001, ISO 14001 and OHSAS 18001.
- 6)Interface with customers and internal quality team on technical/quality issues and improvement initiatives.
- 7)Perform Risk Assessments and review it periodically to ensure compliance and suitability of the processes and procedures.
- 8)Develops, establishes and maintains quality assurance programs, policies, processes, procedures and controls ensuring that performance and quality of products conform to established standards, agency guidelines and customer requirements.
- 9)Provides factory support to identify and resolve issues associated with purchased parts, materials and manufacturing.
- 10)Prepare "Failure Analysis Report" to customer and work as team within all cross-function for corrective action plan on customer return.
- 11)Interface with manufacturing, engineering to ensure compliance to quality procedure and determine responsibilities and solutions when required.
- 12)Responsible to manage " Safety Committee" to ensure safe work environment through implementation of safety awareness programs and compliance with internal safety standard.
- 13)Responsible to manage "Chemical Waste Management" of SW104,SW110,SW409, SW410 and SW430.

Project achievement:

- 1)Lead the team as "Quality Management Representative" to obtain ISO9001 re-certification successfully.
- 4)Achieved and maintaining out going quality level at 100DPPM by leading continues improvement group of cross function internal and key person to representing voice of customer.
- 5)Successfully maintaining and controlling the control operational budget by achieving 100% of cross function team KPI between the baseline value and 10% improvement on overall KPI indicators.
- 6)Improve the RMA(Reject material from customer) with implementation of poka-yoke projects by liaising with engineering dept on the continues process improvement at function test station.
- 7)Project leader and successfully completed NPI&NPD of " telecommunication "Box-build" product to RFP(release to production) stage.
- 8)Successfully implementation of 8D and statistical problem analysis as SPC and FMEA in the workshop of supplier quality improvement.
- 9)Lead a group of cross-function teams for ISO14001 and OHSAS18001 certification.

Singatronics(M) Sdn.Bhd (April 2010 - April 2011)

Position Title (Level) : PRODUCTION MANAGER (Manager)

Specialization : Manufacturing/Production Operations

Role : Management

Industry : PCBA Manufacturing / Production

Monthly Salary : MYR 5300

Work Description :

- 1)Leads production team of 311 personals of 272 direct and 12 indirect employee for SMT,PCBA and Box Build manufacturing line to maximize utilization and meet the production schedules.
- 2)To manage and control all production activities to maximize the use of the organization's resources and meet established production specifications and schedules, volume, cost, and wastage targets and quality standards.
- 3)To ensure daily/monthly output is achievable and manage scheduling of shipping dates for all incoming sales orders.
- 4)To monitor daily/monthly raw material and scarp to achieve high efficiency.
- 5)Plan,priorities and manage production line "schedule maintenance downtime" to minimize disruptions to manufacturing schedules.
- 6)Lead and develop a team of supervisors who are responsible for various production activities such as assembly, machine operation, processing, visual inspection and packaging.
- 7)Monitor and analysis factor as allocate labour management,manufacturing schedules,manufacturing procedures and other considerations to facilitate production processes.
- 8)Chair production continues improvement activity of "Productivity lost issue" as scrap, with management, engineering and other function team.

Project achievement:

- 1) Manage high mix volume manufacturing of more than 8 products per month.
- 2) Successfully achieved 10% reduction in missed shipment by leading a project activities related to strategic purchasing and raw material management by implementing ERP system to minimize unproductive time and operating expenses.
- 3) Developed and track cost improvement projects to reduce production costs by 10% for solder wave process. Improve the MU(machine utilization) at 20% and electricity utilization.
- 4) Efficiently set and control operational budgets on headcount allocation per product line, capacity planning and production resource management.
- 5) Successfully plan work flow, manage multiple priorities and meet daily production targets while consistently reducing downtime of new RFP line.
- 6) Set up health and safety audit procedures and improve safety efficiencies with maintaining the KPI indicator of "Lost day Case" and "Major Accident" at zero.

TEXES INSTRUMENT Sdn.Bhd (March 2006 - March 2010)

Position Title (Level) : EQUIPMENT ENGINEER (Senior Executive)

Specialization : Manufacturing/Production Operations

Role : Management

Industry : Semiconductor/Wafer Fabrication

Monthly Salary : MYR 4025

Work Description :

- 1) Lead and manage a team of 24 Technicians and 3AE to provide speedy maintenance and equipment stability to support to production equipment of FOL/EOL RFID.
- 2) To plan, develop, and implement an effective "Preventive Maintenance" program for machine tooling and equipment of FOL/EOL of RFID.
- 3) To identify maintenance spares required inventory, establish procedure of re-order levels, placing re-orders, recommend dead or obsolete stocks to be purged.
- 4) Ensure conformance all internal/ external audits (EHS/ ISO/ TS/ Customer).
- 5) Plan, organize and manage maintenance resources to optimize manpower utilization, machine uptime and OEU.
- 6) Process and capacity buyoff for new tooling/equipment and able to maintain with recorded tracking system.
- 7) To lead and initiate improvement program on equipment stability, defect density, manufacturing cost deduction, production efficiency and product quality.
- 8) Coordinate and work closely with different vendors and department on rectifying excursion.
- 9) Analysis on equipment hard down escalation and conduct basic and second level training for new line engineers.
- 10) To work together with Product / Process Engineer/NPD Engineer on NIP & NPD.
- 11) To prepare maintenance budget based on forecast of production volume.
- 12) Representative of "Equipment engineering" for MRB(Material Review Board) and CCRB(Customer complain review board) to enhance product quality and DPPM indicator.

Project achievement:

- 1) Implementation of "Revolutionize Maintenance" such as machine upgrade or modification with using of alternate parts when original part became obsoleted.
- 2) Analysis life span for equipment part with "predictive maintenance" engineering data tracking for better product quality and equipment uptime.
- 3) Qualified new equipment of Automated Handler System, K&S die bonder and Thermal Shock Cycle oven for FOL/EOL RFID.
- 4) Project coordinator of "Die bonder Capital program" to support NUB (number unit build) to support business capacity of FOL RFID.
- 5) Implementation of "deep cut lead screw" for glob top for better UPH (increased of 10%) and yield improvement of 0.5% of FOL RFID.
- 6) Yield improvement for "incomplete symbol" and "tilled antenna" process. Yield lost of 0.10% been improved to 0.01% of total yield lost of EOL RFID.
- 7) Qualified "Lead Free solder" and process realization of reflow profile for HELLER reflow oven at solder curing process on RFID LF EOL "new business" project.
- 8) Competition of equipment UPH improvement of solder dispenses equipment for 13k per shift to 16k per shift to meet customer demand for EOL RFID.
- 9) Key player in "Broken Metal Line" of customer complain issue. Develop the contaminate/long team plan on the equipment upgrade and PFMEA. Lead a group of peoples on PDCA which involved of equipment & process improvement (internal team) and work together with R&D & Customer (external team) on the "substrate design" change. ROI (Return of investment) of this project has improved 80% of CRU and won the confident level of customer.
- 10) Champion of "2009 TIM Assembly/RFID/PMPD Technical Conference".
- 11) Implemented "3rd head dispense system" to upgrade solder dispensing mechanism at SMT line to maximize solder dispense capacity and UPH.
- 12) Lead a group of TI RFID Dept people on OHSAS 18001 audit and certification.

INTEL TECHNOLOGY Sdn.Bhd (1996 - 2006)

Position Title (Level) : PROCESS ENGINEER (Senior Executive)

Specialization : Manufacturing/Production Operations

Role : Process Engineer

Industry : Semiconductor/Wafer Fabrication

Monthly Salary : MYR 3500

Work Description :

- 1) Responsible for CPU Pentium#4 product development, validation for mobile and microprocessor product. My job was more to drive product health indicator and to improve the yield and achieve "epoxy under fill process" of ATM (Assembly & Test Manufacturing).
- 2) Responsible for supervising the activity of process and equipment team for equipment as Asymtek, Tiros, Daynapace, VIP BTU, LKT and QPR Fuji at epoxy under fill.
- 3) Provide effective coaching to line MTE on troubleshooting and capable to handle particular area excursions management and drive for prevention of reoccurrence. My

job was to drive the focus team on module continuous improvement programs and module competency development.

- 4) Responsible of NPI&NPD activity and analysis the HVI manufacturing capability and process stability for new product and equipments at production line.
- 5) Improve MU(machine utilization) base on data analysis of MTBA/MTBF and Reject pareto chart.
- 6) Lead a group of Focus team for FOL Pentium#4 platform..
- 7) Implement and monitor performance of SPC for the critical process.
- 8) Evaluate and analyses on in-house quality problems or customer returned parts together with QA engineer.
- 9) Evaluate and analyses new material in term of costing and quality.
- 10) Conduct DOE,PFMEA and WHY-WHY analyze with cross function to evaluate analyses new process parameter and monitor the effectiveness.
- 11) Assessed manpower and material levels to determine production schedules, mainly job level focus to establish operating procedures and continues improvement on yield.

Project achievement:

- 1) Successfully transferring new product development of Pentium#4 and technology transfer such as epoxy underfill and HIS for rap 46.1 to rap 47.8 process.
- 2) Improvement of UPH (unit process per hour) for epoxy Pentium#3&4 process (changed of under fill heater form IR type to heater block type). Previous UPH is 11k unit/shift/day to new UPH of 13.8k units/shift/day.
- 3) Key player in successful implementation of SSM(Self Sustain Maintenance) and people management for a group of staff at epoxy department (10 technicians and 2 associated engineers). Lead the group for process development and PM upgrade activity and people development.
- 4) Design of boat guide and system to prevention oven crash for TIROS oven.(Prevent from oven crash which impact to productivity and yield.)

Educational Background:

Graduation Date: 2003

Bachelor's Degree of Engineering (Electrical/Electronic)

Major : Major in Electronic
Institute/University : University of Lincoln, United Kingdom
Grade : Grade B/2nd Class

Graduation Date: 1999

Advanced/Higher/Graduate Diploma of Engineering (Electrical/Electronic)

Major : Major in Electrical
Institute/University : MATRIX Qualification Center, Malaysia
Grade : Grade B/2nd Class

Skills:

Skill	Years	Proficiency
Computer Hardware Maintenance	>5	Advanced
Autocad Application	>5	Advanced
Electrical Trouble Shooting	>5	Advanced
Engineering Management	>5	Advanced
Statistical Process Control	>5	Advanced
Leadership And Management	>5	Advanced
ISO	>5	Intermediate
FMEA	>5	Advanced
Internal Quality Audit	>5	Advanced
Electronic Circuit Troubleshooting	>5	Advanced

Languages:

(Proficiency: 0=Poor - 10=Excellent)

Language	Spoken	Written
English	8	8
Bahasa Malaysia	8	8
Tamil	8	0

Personal Particulars & Preferences:

Date of Birth : 20 Dec 1974
 Nationality : Malaysia
 Gender : Male
 IC No. : 741220-07-5345
 Possess Own Transport : Yes
 Availability : Immediately.

Additional Info:**CAREER OBJECTIVE:**

To apply my knowledge, experience, skills, fast learning abilities and trouble-shooting capability in such as strong and esteemed organization.

Other course:

1)Certificate in Electronic Technician Course (PIE, Perak)	Dec 1994
2)Microprocessor language (Kolej Kota, Perak)	May 1996
3)Course in Team Building (PSDC, Penang)	Dec 1998
4)Wordstar professional (WIT, Perak)	May 1998
5)Programmable Logic Controllers (PSDC, Penang)	Sept 1999
6)Cardiopulmonary Resuscitation(CPR) Program (Earthwin, Penang)	July 1999
7)Pneumatic&Electo-pneumatic (Info-genius, Penang)	Oct 2002
8)Goshin-Ryu-KarateDo Association Mal (3rtKyu Brown belt)	Sept 1995

Equipment courses:

- | | |
|--|-----------|
| 1) Schlumberger Automated System (Precision Encapsulation and Cure system Maintenance) | Sept 1996 |
| 2) Kulicke and Soffa Industries, Inc. (8060 Wedge Bonder Maintenance) | Sept 1998 |
| 3) Tيروس Semiconductor Equipment (Level II Tيروس 800 BTI Vertical Oven) | June 1999 |
| 4) BTU VIP-98 horizontal Oven Equipment (Level II Software and Maintenance) | June 1999 |
| 5) Asymtek (FC-PGA, C4 & 1262 Epoxy L2, L3 and L4 Maintenance) | July 2000 |
| 6) Asymtek Millennium Software Configuration and software Programming. | Sept 2000 |
| 7) Sonic SAM Inspection System (Ultrasonic Scanning Acoustic Microscope) | Mar 2001 |
| 8) LKT 2000 Equipment (Level II LKT 2000 Maintenance) | June 2003 |
| 9) Fuji QP203E SPM/SRM Equipment (Level II Fuji Maintenance) | July 2003 |

Computer experience:

- a) Electronic Workbench V3.0, AutoCAD and Matlab simulation.
- b) MS-DOS, MS-office and WINDOR NT/ME/98/2000/XP
- c) VHDL and Verilog HDL for logic, simulation and test vectors.
- d) Hardware and computer assembling and configuration.

STRENGTHS:

- a) Exceptional versatility and adaptability.
- b) Demonstrated effective oral and written communication skills with the ability to communicate technical information to non-technical personnel.
- c) Ability and willingness to work on multiple projects at one time and be able to adapt to changing priorities.
- d) Demonstrated ability to analyze business/technical problems and implement information technology solutions in accordance with business needs.
- e) Management of subcontracts, knowledge of multi-discipline construction methods and practices.
- f) Ability to work with team members to deliver on time and on budget-committed results to customers.
- g) Demonstrated working knowledge of multiple business disciplines.
- h) Superlative communication and team-building skills.
- i) Experience in high (405kV), medium and low (24V-5V) voltage systems design including specifying, power distribution, schematics, layouts and grounding system.
- j) Dedication and drive as a hard-working individual.
- k) Strong communication and project management skills, work closely with internal cross functional team, customers, vendors and suppliers to meet project deadline in a fast paced environment

References

Name : CK LEE
Relationship : Previous Dept Manager
Position : Dept Head(QST) of RFID TI
Company : Texas Instrument Snd.Bhd
Telephone : 6-012-2816219
Email : ck.lee@ti.com

Name : Vnesh
Relationship : Friend
Position : Operation Manager
Company : Spectrum Integrated Technologies Sdn Bhd
Telephone : 6-016-7479229
Email : vnesh@spectrum-intech.com